

A1
cont.

whereafter the flexible foil (6) is detachably secured, on the side of the conductive layer (4), to the substrate (7), after which the other substrate (9) is removed.

4. (amended) A method as claimed in claim 1, characterized in that a number of semiconductor bodies (1) are simultaneously formed so as to be connected to each other, and subsequently secured, on a side opposite the connection regions (2), to an elastic foil (11), after which they are separated by means of sawing or etching, whereafter the elastic foil (11) is stretched uniformly in all directions after which the individual semiconductor bodies (1) are provided and secured onto the flexible foil (6).

5. (amended) A method as claimed in claim 1, characterized in that prior to the provision of the semiconductor body (1) on the flexible foil (6), a part thereof that is situated between the apertures (5) in the insulating layer (3) is provided with an electrically insulating fixing agent (12) on which the semiconductor body (1) is placed and the height of which determines the distance between the semiconductor body (1) and the flexible foil (6).

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conc.

6. (amended) A method as claimed in claim 1, characterized in that after the provision of the semiconductor body (1) on the flexible foil (6), a liquid, electrically insulating synthetic resin (13) is provided between the semiconductor body (1) and the flexible foil (6) as well as around the semiconductor body (1), which synthetic resin is subsequently cured.

A2

8. (amended) A method as claimed in claim 1, characterized in that a solid photoresist layer (3) is used for the electrically insulating layer (3).

9. (amended) A method as claimed in claim 1, characterized in that for the material of the electrically insulating layer (3) use is made of a polyimide, and for the material of the conductive layer (4) use is made of copper.

10. (amended) A semiconductor device (10) which can suitably be used for surface mounting and which is obtained using a method as claimed in claim 1.

REMARKS

The foregoing amendments to the claims were made solely to avoid filing the claims in the multiple dependent form so as to